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	Under the Paperwork Reduction Act of 1995, no persons are required to r	Approve U.S. Patent and Tradomar	PTO/SB/30 (10-0 d for use through 10/31/2002. OMB 0861-00 k Office; U.S. DEPARTMENT OF COMMERC
	REQUEST	Application Number	on unless it displays a valid OMB control number 09/387,857-Conf. #3099
	FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL Address to: Commissioner for Patents Box RCE	Filing Date	September 1, 1999
		First Named Inventor	Fumitaka Sugaya
		Group Art Unit	2822
		Examiner Name	C. Novacek
	Washington, DC 20231	Attorney Docket No.	21776-00039-US
	This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application. Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.		
	Submission required under 37 CFR 1.114 a. X Previously submitted		
	i. X Consider the amendment(s)/reply under 37 CFR 1.116 previously filed on (Any unantered amendment(s) referred to above will be entered). November 25, 2002		
	ii. Consider the arguments in the Appeal Brief or Reply Brief previously filed on iii. Other		
	b. x Enclosed		
	i. Amendment/Repty		
	iiAffidavit(s)/Declaration(s)		
	lii. Information Disclosure Statement (IDS)		
01/14/2000 DBROWN	iv. x Other Othe		
01 FC:1801 74	FC: 1801 740, 00 CH a. Suspension of action on the above-identified application is requested under 37 CFR 1.103(c) for a period of months. (Period of suspension shall not exceed 3 months; Fee under 37 CFR 1.17(l) required) b. Other		
ĺ	3. Fees The RCE fee under 37 CFR 1.17 (e) is required by 37 CFR 1.114 when the RCE is filed.		
	a. X The Director is hereby authorized to charge the following fees, or creditent were profite by ED		
	ii. X Extension of time fee (37 CFR 1.138 and 1.17)		DEC 2 3 2002
	iii. Other	' '	ECHNOLOGY CENTER 2800
ł	b. Check in the amount of \$ enclosed		
	c. Payment by credit card (Form PTO-2038 anclosed)		
	SIGNATURE OF APPLICANT, AT	TORNEY, OR AGENT RE	QUIRED

Registration No. (Attorney/Agent)

27,369

December 23, 2002

Namo (Print/Type)

Signaturo

George R. Pettit

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039-US ATENT) 123/03

Docket No.: 21776-00039-US

Group Art Unit: 2822

Examiner: C. Novacek

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Fumitaka Sugaya

Application No.: 09/387,857

Filed: September 1, 1999

For: A SEMICONDUCTOR DEVICE AND A

METHOD OF MANUFACTURING THE

SAME

FIRST PRELIMINARY AMENDMENT

Box Non-Fee Amendment Commissioner for Patents Washington, DC 20231

Dear Sir:

Prior to examining the above-identified RCE application, entry of the previous Amendment under § 1.116 is requested.

Applicants have submitted the changes to the claims under previous § 1.116 in an effort to avoid the rejection under 35 U.S.C. § 112.

As to the rejection of claim 36 under 35 U.S.C. § 102(e) as being unpatentable over Schoenfeld et al. (U.S. Pat. No. 6,010,932), claim 36 is believed to be distinguished from the reference based on, among other things, the recitation of the third step of etching the first conductive film. The first conductive film is divided to conform to a shape of one of the openings until the insulating film region is reached. The result is a hole in the surface of the conductive film exposing the insulating film region. A recess is formed in the surface of the divided first conductive film which conforms to a shape of the other opening.

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It is submitted that the Schoenfeld et al. reference does not show the foregoing steps which provides for a divided conductive film conforming to the shape of an opening which reaches the insulating film region.

Withdrawal of the rejection of claims 38 and 39 under 35 U.S.C. § 103(a) as being unpatentable over Komori et al. (U.S. Pat. No. 5,300,802) in view of Wolf et al. is requested. The acknowledged deficiency in Komori et al., regarding patterning a first conductive layer, acknowledges the fact that the fourth step of claim 38 of providing a mask pattern having at least first and second openings, is not disclosed. Therefore, the fifth step of etching the first conductive film (after patterning) until the element isolation structure is exposed in first and second openings can not be disclosed as well.

Claim 38 is a method claim, and while similar structures may be formed by other methods, the similar resulting structure does not necessarily anticipate or render obvious the method for creating such structures. Accordingly, it is requested that the claim be examined with respect to its recitation of distinct method steps not shown in the reference.

While Wolf may be cited for the proposition that lithography is a conventional method of patterning semiconductor structures, it is not seen how it discloses the specific method steps 4 and 5 of rejected claim 38 to create the first and second openings in the conductive film and simultaneously form a hole extending through the first conductive film below the second opening.

As the application has been previously indicated to contain allowable subject matter, the Examiner is urged to contact the undersigned at the telephone number below to conduct a personal interview in the event that any further cooperation will result in alloward in the ECEIVED application.

DEC 2 3 2002

Dated: December 23, 2002

Respectfully submitted, TECHNOLOGY CENTER 2800

George R. Pettit, Reg. No. 27, 369

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